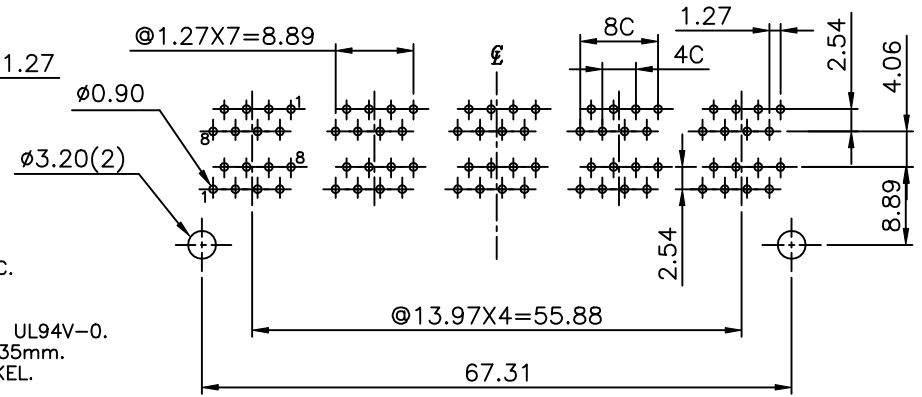
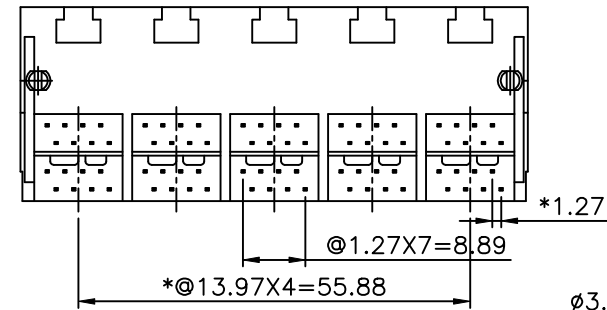
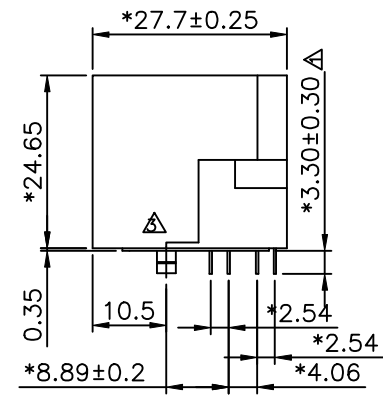
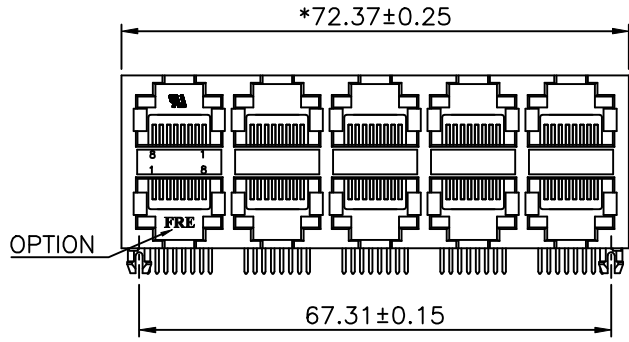


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		EC DIM	Ming-Wei 04/15/02	
△		ADD PART NO.	Qianpu 6/19/04	
△		MODIFY DRAWING	QIULER 12/03/04	
△		MODIFY DRAWING	QIULER 01/25/05	



NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 50 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER : 10 LBS MIN.

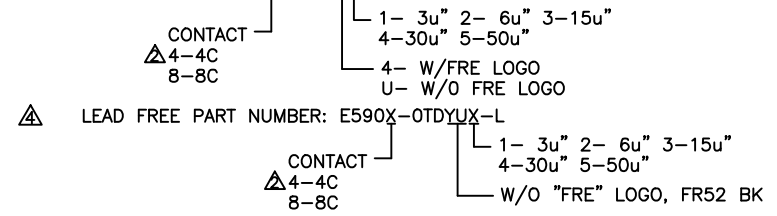
ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
- OPERATION: 0°C TO 70°C.

MATES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.
CUL FILE NO. 163191

PART NUMBER: E590X-OTDOXX



PC Board Layout Component Side Shown
PC Board Thickness=1.6mm

DETACHED LISTS	← MM (INCH) →	DFTO Ming-Wei	DATE 04/09/2002
	TOLERANCES EXCEPT AS NOTED	CHKD QIANPU	DATE2006/1/25
		MFO	DATE
		APPVLU SHENG	DATE2006/1/25
		MATERIAL :	
	ANGLES ± 0.5	QT'Y :	
	THIRD ANGLE PROJECTION	FINISH :	
		SCALE : 1.5 : 1	

FULL RISE ELECTRONIC CO., LTD

TITLE STAMPED PIN III
STACKED GANGED JACK, 2X5

DRAWING NO. GE593B55	SIZE A3	REV 4
/PART NO. SEE NOTE		
DO NOT SCALE DRAWING	SHEET 1	OF 1